

# PARA LIGHT ELECTRONICS CO., LTD.

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# DATA SHEET

PART NO.: L-C195JRJGCT

REV: <u>A / 5</u>

CUSTOMER'S APPROVAL: \_\_\_\_\_ DCC: \_\_\_\_

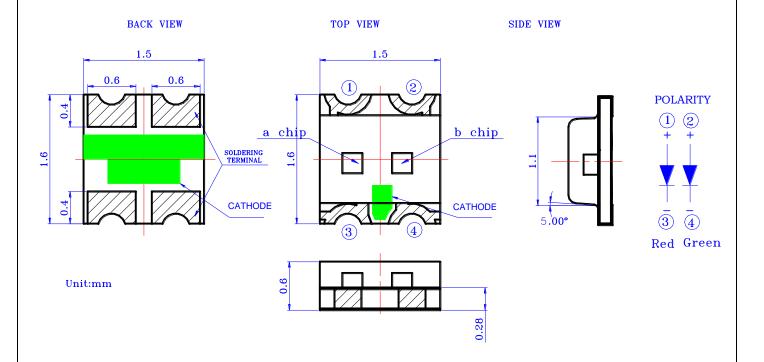


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#### PACKAGE OUTLINE DIMENSIONS



#### Notes:

- 1. a chip: Red; b chip: Green
- 2. All dimensions are in millimeters.
- 3. Tolerance is  $\pm$  0.1mm (.004") unless otherwise noted.

#### Features

- **★** Dual color, top view, wide view angle Chip LED.
- \* Package in 8mm tape on 7" diameter reels.
- \* Compatible with automatic Pick & Place equipment.
- \* Compatible with Reflow soldering and Wave soldering processes.
- \* EIA STD package.
- \* I.C. compatible.
- \* Pb free product.
- **★** Moisture sensitivity level: 3



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### Chip Materials

Chip	Light Color	Dice Material	Lens Color	
a	JR: Red	AlInGap	Water Clear	
b	JG: Green	AlInGap		

# • Absolute Maximum Ratings (Ta=25°C)

Cymbol	Parameter	Rating		Unit	
Symbol	rarameter	Green	Red	Ollit	
PD	Power Dissipation	60	75	mW	
Ipf	Peak Forward Current	60	80	mA	
IPF	(1/10 Duty Cycle, 0.1ms Pulse Width)	00			
IF	Continuous Forward Current	30	30	mA	
$V_R$	Reverse Voltage	5	5	V	
ESD	Electrostatic Discharge Threshold (HBM) <sup>Note A</sup>	2000	2000		
Topr	Operating Temperature Range	-40 ~ +85		°C	
Tstg	Storage Temperature Range	-40 ~ +85		°C	

Note A:

HBM: Human Body Model. Seller gives no other assurances regarding the ability of to withstand ESD.

# • Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Green	Red	Unit	Test Condition	
	Min.	IV	11.2	45	mcd	IF=20mA
Luminous tensity	Тур.		30	100		
	Max.		71	280		
Viewing Angle	Typ.	2θ1/2	130		deg	Note 2
	Min.	λd	567	625		IF=20mA
Dominant Wavelength	Тур.		570	631	nm	
	Max.		576	635		
Spectral Line Half-Width	Тур.	Δλ	15	17	nm	
	Min.	VF	1.7	1.7	V	IF =20mA
Forward Voltage	Typ.		1.9	1.9		
	Max.		2.1	2.1		
Reverse Current	Max.	IR	5	5	μA	VR = 5V



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#### Notes:

- 1. Luminous intensity is measured with a light sensor and filter combination that proximities the CIE eye-response curve.
- 2.  $\theta$  1/2 is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- 3. The dominant wavelength  $\lambda$  d is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.
- 4. Caution in ESD:
  - Static Electricity and surge damages the LED. It is recommended use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.
- 5. Major standard testing equipment by "Instrument System" Model: CAS140B Compact Array Spectrometer and "KEITHLEY" Source Meter Model: 2400.

### • Typical Electro-Optical Characteristics Curves

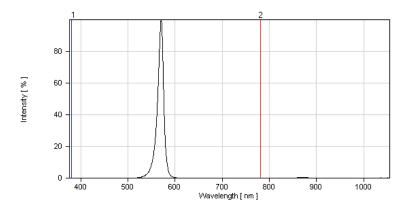


Fig.1 Green Relative Intensity vs. Wavelength

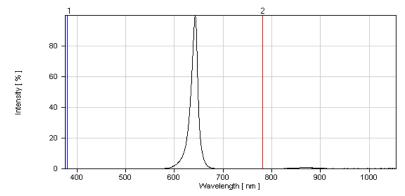


Fig.1 Red Relative Intensity vs. Wavelength



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### Green Typical Electro-Optical Characteristics Curves

(25°CAmbient Temperature Unless Otherwise Noted)

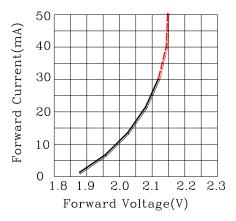


Fig.2 Forward Current vs.Forward Voltage

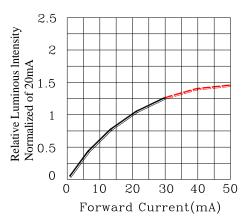


Fig.4 Relative Luminous Intensity vs.Forward Current

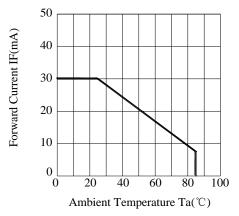


Fig.6 Forward Current Derating Curve

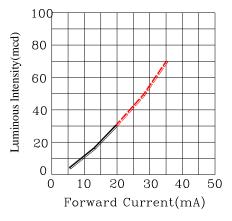


Fig.3 Luminous Intensity vs.Forward Current

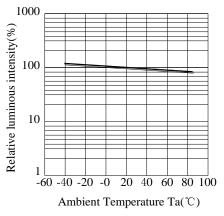


Fig.5 Luminous Intensity vs. Ambient Temperature

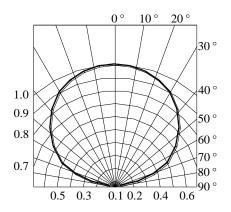


Fig.7 Relative Intensity vs.Angle



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### Red Typical Electro-Optical Characteristics Curves

(25°CAmbient Temperature Unless Otherwise Noted)

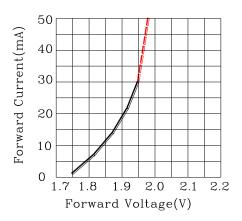


Fig.2 Forward Current vs.Forward Voltage

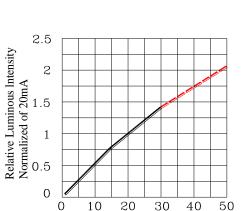


Fig.4 Relative Luminous Intensity vs.Forward Current

Forward Current(mA)

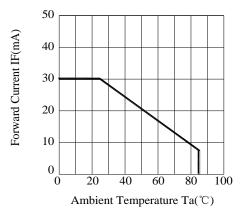


Fig.6 Forward Current Derating Curve

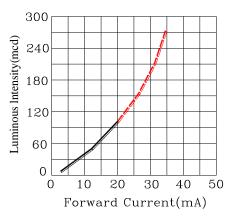


Fig.3 Luminous Intensity vs.Forward Current

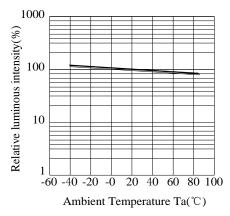


Fig.5 Luminous Intensity vs. Ambient Temperature

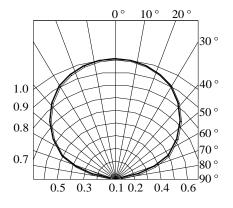


Fig.7 Relative Intensity vs.Angle



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### Label Explanation



ITEM CODE:PARRA LIGHT

PART NO: L-C195JRJGCT

IV --- Luminous Intensity Code

LOT NO: <u>EM S L 12 09</u> 0110 A B C D E F

A---EM: Emos Code

B---S:SMD

L---Local

D---Year

E---Month

F---SPEC.

#### PACKING QUANTITY OF BAG:

3000pcs for 150, 170, 110, 155, 115 series

4000pcs for 191 series

5000pcs for 192 series

DATE CODE: <u>2012</u> <u>09</u> <u>10</u>

G H I

G--- Year

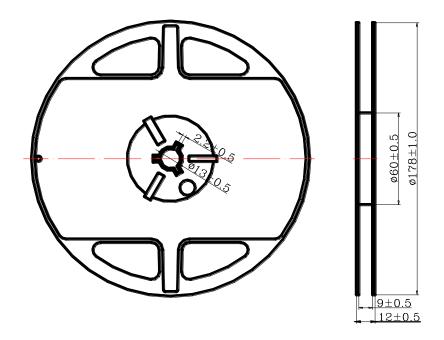
H--- Month

I --- Day



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### Reel Dimensions



#### Notes:

- 1. Taping Quantity: 3000pcs
- 2. The tolerances unless mentioned is  $\pm 0.1$ mm, Angle  $\pm 0.5^{\circ}$ , Unit: mm.

DRAWING NO.: DS-78-14-0004

DATE: 2021-11-26

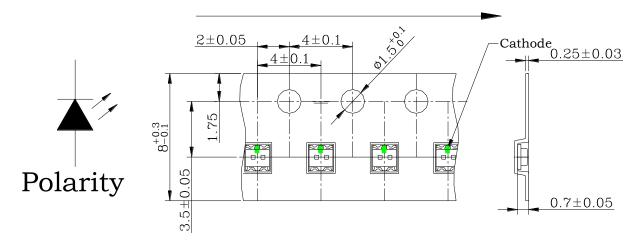
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Package Dimensions Of Tape And Reel

# Progressive direction



Notes: All dimensions are in millimeters.

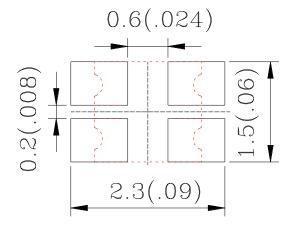


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### Cleaning

- \* If cleaning is required, use the following solutions for less than 1 minute and less than 40°C.
- \* Appropriate chemicals: Ethyl alcohol and isopropyl alcohol.
- \* Effect of ultrasonic cleaning on the LED resin body differs depending on such factors as the oscillator output, size of PCB and LED mounting method. The use of ultrasonic cleaning should be enforced at proper output after confirming there is no problem.

### Suggest Soldering Pad Dimensions





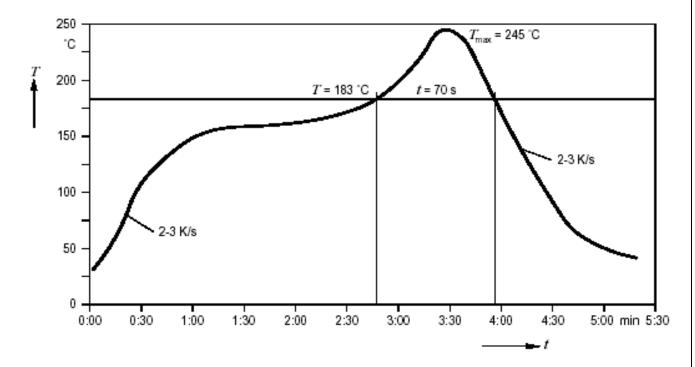
Direction of PWB camber and go to reflow furnace



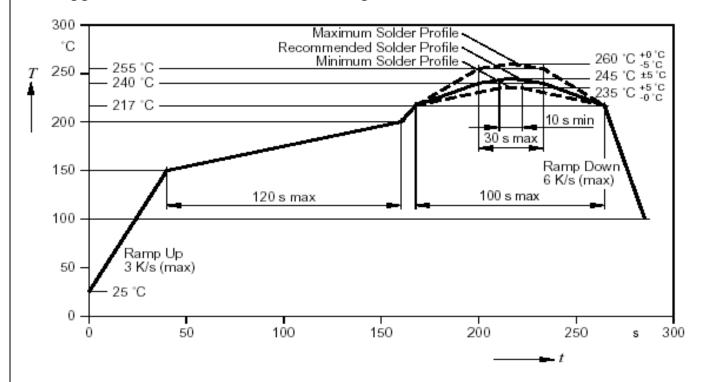
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### • Suggest Sn/Pb IR Reflow Soldering Profile Condition:



### • Suggest Pb-Free IR Reflow Soldering Profile Condition:





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#### Bin Code List

Luminous Intensity (IV), Unit: mcd@20mA					
Red (a chip)			Green(b chip)		
Bin Code	Min	Max	Bin Code	Min	Max
P	45	71	L	11.2	18
Q	71	112	M	18	28
R	112	180	N	28	45
S	180	280	P	45	71

Tolerance of each bin are  $\pm 15\%$ 

Dominant Wavelength (Hue), Unit: nm@20mA				
Green(b chip)				
Bin Code	Min	Max		
GA	567	570		
GB	570	573		
GC	573	576		

Tolerance of each bin are  $\pm 1$ nm

### **CAUTIONS**

#### 1. Application Limitation:

The LED's described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household application). Consult PARA's sales in advance for information on application in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LED's may directly jeopardize life or health (such as airplanes, automobiles, traffic control equipment, life support system and safety devices).

#### 2.Storage:

Do not open moisture proof bag before the products are ready to use.

Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.

If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment: 60±5°C for 24 hours



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#### 3.Soldering

Do not apply any stress to the lead frame during soldering while the LED is at high temperature.

Recommended soldering condition.

Reflow Soldering:

Pre-heat 120~150 ℃, 120sec. MAX., Peak temperature: 240 ℃ Max. Soldering time: 10 sec Max.

Soldering Iron: (Not recommended)

Temperature 300 °C Max., Soldering time : 3 sec. Max.(one time only), power dissipation of iron : 20W Max. use SN60 solder of solder with silver content and don't to touch LED lens when soldering.

Wave soldering:

Pre-heat  $100 \, \text{C}$  Max, Pre-heat time  $60 \, \text{sec.}$  Max, Solder wave  $260 \, \text{C}$  Max, Soldering time  $5 \, \text{sec.}$  Max. preformed consecutively cooling process is required between  $1^{\text{st}}$  and  $2^{\text{nd}}$  soldering processes.

#### 4. Lead-Free Soldering

For Reflow Soldering:

- 1. Pre-Heat Temp:150-180°C,120sec.Max.
- 2. Soldering Temp: Temperature Of Soldering Pot Over 230°C,40sec.Max.
- 3 Peak Temperature: 260 °C , 5 sec.
- 4. Reflow Repetition:2 Times Max.
- 5. Suggest Solder Paste Formula 93.3 Sn/3.1 Ag/3.1 Bi /0.5 Cu

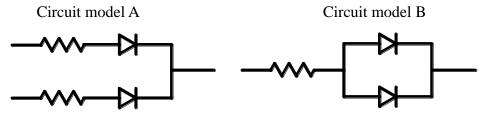
For Soldering Iron (Not Recommended):

- 1. Iron Tip Temp:350°C Max.
- 2. Soldering Iron:30w Max.
- 3. Soldering Time: 3 Sec. Max. One Time.

#### For Dip Soldering:

- 1. Pre-Heat Temp:150°C Max. 120 Sec. Max.
- 2. Bath Temp:265°C Max.
- 3. Dip Time: 5 Sec. Max.

#### 5. Drive Method



- (A)Recommended circuit.
- (B) The difference of brightness between LED's could be found due to the Vf-If characteristics of LED.